

SOLDER RESIST COMPOSITION AND PRINTED CIRCUIT BOARDS**ABSTRACT OF THE DISCLOSURE**

A solder resist composition comprises an acrylate of novolac type epoxy resin and an imidazole curing agent and has a viscosity of 0.5-10 Ps·s adjusted with glycol ether type solvent. A printed circuit board is formed by using such a solder resist composition.

NO SUITABLE FIGURE

This Sheet Has Been Replaced



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